

Examine: 612

0

AN 1988-116784 [17] WPIDS
DNN N1988-088674 DNC C1988-052680
TI Fine copper wire mfr. contg. titanium - by drawing and annealing ingot
after casting in vacuum or non-oxidising atmos..
DC L03 M26 U11 X12
PA (FURU) FURUKAWA ELECTRIC CO LTD; (FURU-N) FURUKAWA TOKUSHU KINZOKU
CYC 1
PI JP 63064211 A 19880322 (198817)* 6p
JP 04064121 B 19921014 (199245) 8p
ADT JP 63064211 A JP 1986-208896 19860905; JP 04064121 B JP 1986-208896
19860905
FDT JP 04064121 B Based on JP 63064211
PRAI JP 1986-208896 19860905
AB JP 63064211 A UPAB: 19930923
Fine Cu wire comprises 0.1-9 ppm Ti, 0.2-9.5 ppm as a total amt. of one
or
Ta, more of respectively 0.1-9 ppm Nb, Mg, Ca, rare earth elements, Hf, V,
Pd, Pt, Au, Cd, B, Al, In, Si, Ge, Pb, P, Sb, and Bi, and
balance Cu. Th purity of balance Cu is 99.999
wt.% or over. The fine Cu wire is made by repeating wire drawing and
annealing the Cu ingot which was cast in vacuum or non-oxidising atmos.,
to specified wire dia., in which final working ratio is made to
70-99.99%,
and annealing is done to be 2-20% elongation. After the annealing, 1-5%
redn. of area is applied to obtain 2-20% elongation.
USE/ADVANTAGE - The fine Cu wire made by the method is used for
bonding wire used in making semiconductor.
0/2